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SEMICONDUCTOR



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PLED

**IRF7416TRPBF(MS)**

**Product specification**

**Features**

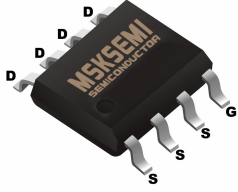
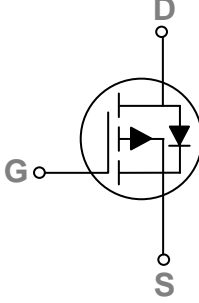

- -30V,-10A, RDS(ON) =15mΩ@VGS = -10V
- Fast switching
- Green Device Available
- Suit for -4.5V Gate Drive Applications

**Application**

- MB / VGA / Vcore
- POL Applications
- Load Switch
- LED Application

BVDSS	RDSON	ID
-30V	15mΩ	-10A

**Reference News**

PACKAGE OUTLINE	Pin Configuration	Marking
 <p>SOP-8</p>		 <p>Note : ****Representative production cycle</p>

**Absolute Maximum Ratings Tc=25°C unless otherwise noted**

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	-30	V
V <sub>GS</sub>	Gate-Source Voltage	±20	V
I <sub>b</sub>	Drain Current - Continuous (T <sub>c</sub> =25°C)	-10	A
	Drain Current - Continuous (T <sub>c</sub> =100°C)	-5.1	A
I <sub>DM</sub>	Drain Current - Pulsed <sup>1</sup>	-40	A
P <sub>D</sub>	Power Dissipation (T <sub>c</sub> =25°C)	2.1	W
	Power Dissipation - Derate above 25°C	0.017	W/°C
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C

**Thermal Characteristics**

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction to ambient	---	60	°C/W

**Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)**
**Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =-250uA	-30	---	---	V
ΔBV <sub>DSS</sub> /ΔT <sub>J</sub>	BV <sub>DSS</sub> Temperature Coefficient	Reference to 25°C , I <sub>D</sub> =-1mA	---	-0.03	---	V/°C
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =-30V , V <sub>GS</sub> =0V , T <sub>J</sub> =25°C	---	---	-1	uA
		V <sub>DS</sub> =-24V , V <sub>GS</sub> =0V , T <sub>J</sub> =125°C	---	---	-10	uA
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> = ±20V , V <sub>DS</sub> =0V	---	---	±100	nA

**On Characteristics**

R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> =-10V , I <sub>D</sub> =-8A	---	15.0	20	mΩ
		V <sub>GS</sub> =-4.5V , I <sub>D</sub> =-5A	---	25.6	32	mΩ
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =-250uA	-1.0	-1.6	-2.5	V
ΔV <sub>GS(th)</sub>	V <sub>GS(th)</sub> Temperature Coefficient		---	4	---	mV/°C
g <sub>fs</sub>	Forward Transconductance	V <sub>DS</sub> =-10V , I <sub>D</sub> =-3A	---	6.8	---	S

**Dynamic and switching Characteristics**

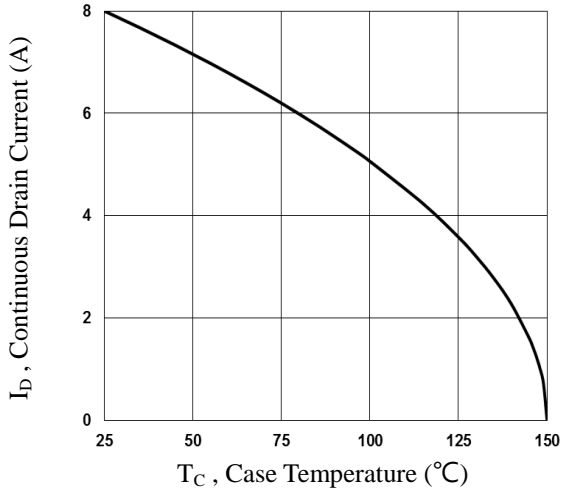
Q <sub>g</sub>	Total Gate Charge <sup>2,3</sup>	V <sub>DS</sub> =-15V , V <sub>GS</sub> =-4.5V , I <sub>D</sub> =-5A	---	11	---	nC
Q <sub>gs</sub>	Gate-Source Charge <sup>2,3</sup>		---	3.4	---	
Q <sub>gd</sub>	Gate-Drain Charge <sup>2,3</sup>		---	4.2	---	
T <sub>d(on)</sub>	Turn-On Delay Time <sup>2,3</sup>	V <sub>DD</sub> =-15V , V <sub>GS</sub> =-10V , R <sub>G</sub> =6Ω I <sub>D</sub> =-1A	---	5.8	---	ns
T <sub>r</sub>	Rise Time <sup>2,3</sup>		---	18.8	---	
T <sub>d(off)</sub>	Turn-Off Delay Time <sup>2,3</sup>		---	46.9	---	
T <sub>f</sub>	Fall Time <sup>2,3</sup>		---	12.3	---	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =-15V , V <sub>GS</sub> =0V , F=1MHz	---	1250	---	pF
C <sub>oss</sub>	Output Capacitance		---	160	---	
C <sub>rss</sub>	Reverse Transfer Capacitance		---	90	---	

**Drain-Source Diode Characteristics and Maximum Ratings**

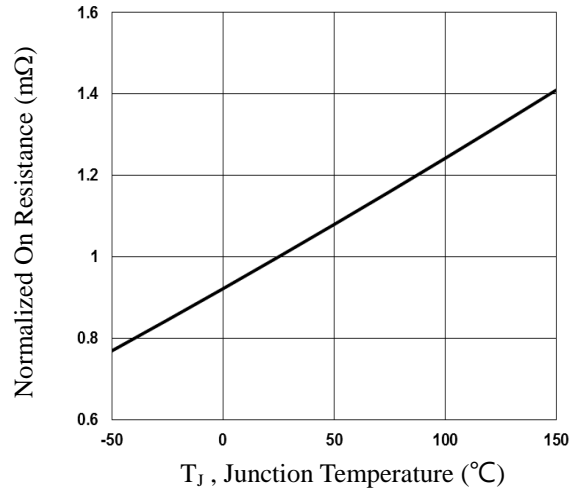
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I <sub>s</sub>	Continuous Source Current	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current	---	---	-10	A
I <sub>SM</sub>	Pulsed Source Current		---	---	-20	A
V <sub>SD</sub>	Diode Forward Voltage	V <sub>GS</sub> =0V , I <sub>S</sub> =-1A , T <sub>J</sub> =25°C	---	---	-1.3	V

Note :

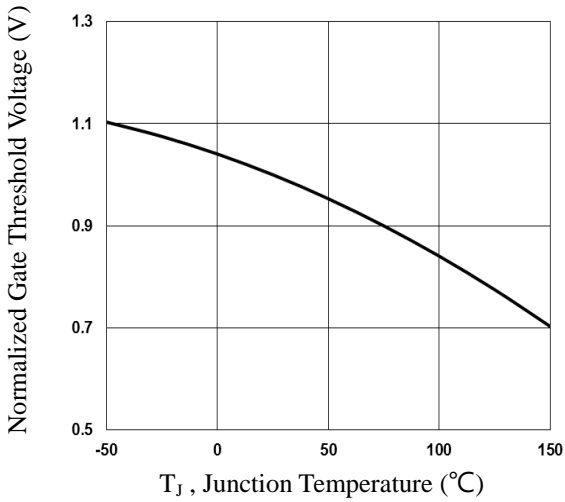
1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%.
3. Essentially independent of operating temperature.



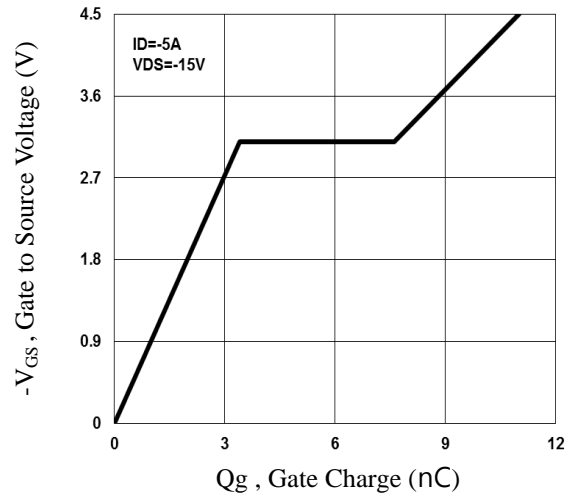
**Fig.1 Continuous Drain Current vs. T<sub>c</sub>**



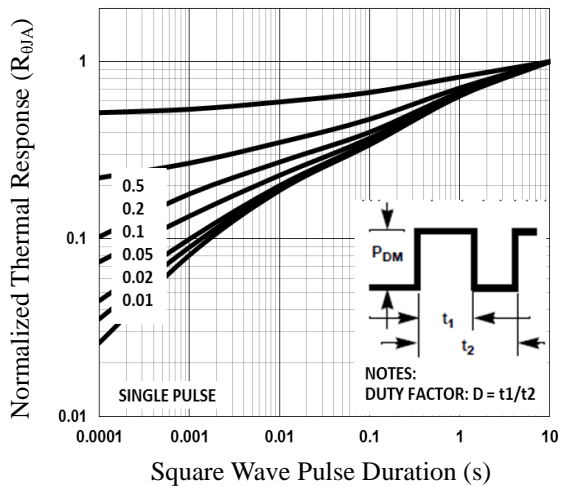
**Fig.2 Normalized R<sub>DS(on)</sub> vs. T<sub>j</sub>**



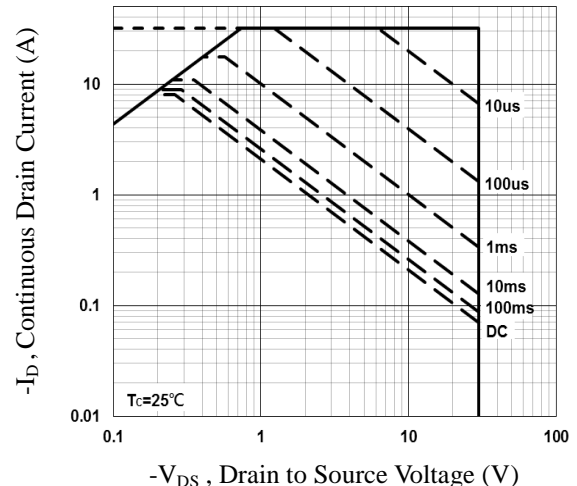
**Fig.3 Normalized V<sub>th</sub> vs. T<sub>j</sub>**



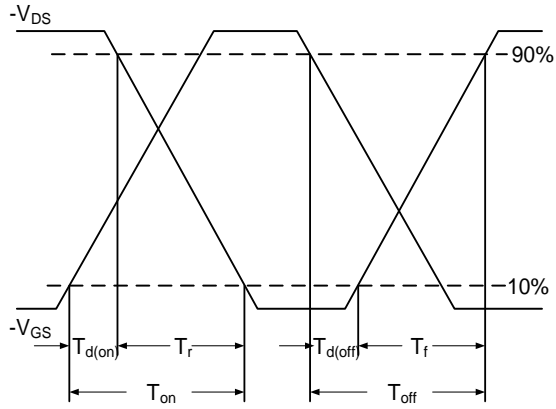
**Fig.4 Gate Charge Waveform**



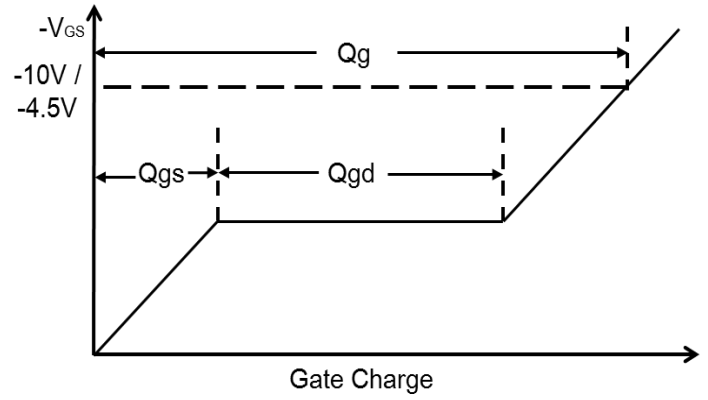
**Fig.5 Normalized Transient Impedance**



**Fig.6 Maximum Safe Operation Area**

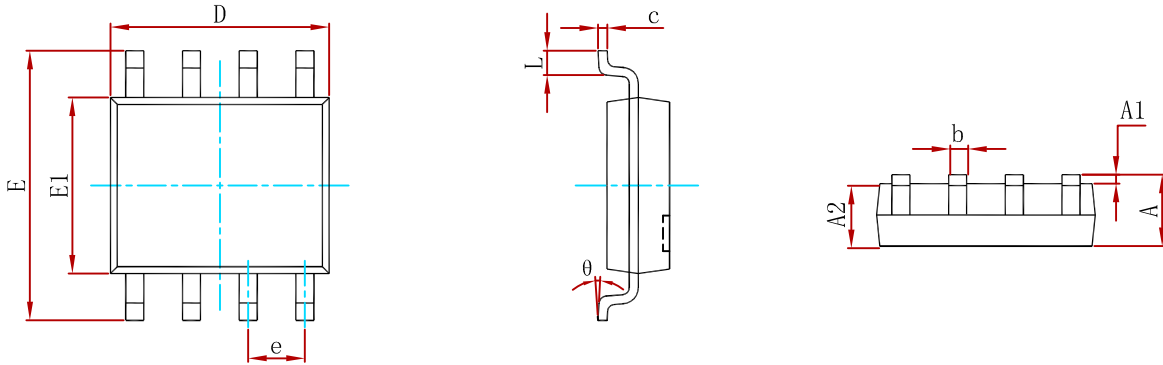


**Fig.7 Switching Time Waveform**



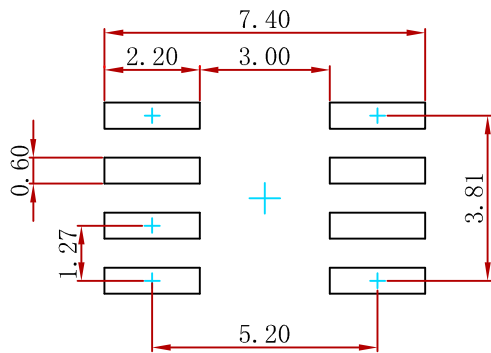
**Fig.8 Gate Charge Waveform**

**PACKAGE MECHANICAL DATA**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.007	0.010
D	4.800	5.000	0.189	0.197
e	1.270 (BSC)		0.050 (BSC)	
E	5.800	6.200	0.228	0.244
E1	3.800	4.000	0.150	0.157
L	0.400	1.270	0.016	0.050
theta	0°	8°	0°	8°

**Suggested Pad Layout**



Note:  
 1. Controlling dimension: in millimeters.  
 2. General tolerance: ± 0.05mm.  
 3. The pad layout is for reference purposes only.

**REEL SPECIFICATION**

P/N	PKG	QTY
IRF7416TRPBF(MS)	SOP-8	3000

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